

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yuji Nishitani</td> <td>01/10/2007</td> </tr> <tr> <td>Tomoshi Ohde</td> <td>12/25/2006</td> </tr> </tbody> </table>		Name	Execution Date	Yuji Nishitani	01/10/2007	Tomoshi Ohde	12/25/2006
Name	Execution Date						
Yuji Nishitani	01/10/2007						
Tomoshi Ohde	12/25/2006						
RECEIVING PARTY DATA							
Name:	Sony Corporation						
Street Address:	7-35, Kitashinagawa 6-chome, Shinagawa-ku						
City:	Tokyo						
State/Country:	JAPAN						
Postal Code:	141-0001						
Name:	Sony Computer Entertainment, Inc.						
Street Address:	2-6-21, Minami-Aoyama, Minato-ku						
City:	Tokyo						
State/Country:	JAPAN						
Postal Code:	107-0062						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11600928</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11600928		
Property Type	Number						
Application Number:	11600928						
CORRESPONDENCE DATA							
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CH \$40.00 11600928

ATTORNEY DOCKET NUMBER:

SCEP 22.828

NAME OF SUBMITTER:

Jeney Han

Total Attachments: 2

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ASSIGNMENT

Docket No. SCEP 22.828

WHEREAS, the below named inventor, ASSIGNOR, has made a certain new and useful invention in:
WIRING BOARD, ELECTRONIC COMPONENT MOUNTING STRUCTURE, AND ELECTRONIC COMPONENT
MOUNTING METHOD

for which

(check one) [] an application is being filed concurrently herewith,

[x] an application for a Patent of the United States was filed on November 16, 2006
and given Application Serial No. 11/600,928

and WHEREAS, SONY CORPORATION having a place of business at 7-35, Kitashinagawa
6-chome, Shinagawa-ku, Tokyo 141-0001 Japan and Sony Computer Entertainment, Inc.

having a place of business at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan

ASSIGNEE is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable
consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR has sold, assigned, transferred and set over, and by
these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and
assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions,
renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions
thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models,
and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the
right to file such applications and the right to claim for the same the priority rights derived from said United States application under
the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international
agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial
property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for
said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of
any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property
protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in
accordance with the terms of this instrument; and

ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed,
and will not execute, any agreement in conflict herewith; and

ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal
representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers,
execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid
the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all
countries.

Full name of sole or first inventor Yuji NISHITANI
Inventor's Signature Yuji Nishitani Date Jan 10th 2007
Residence Kanagawa, Japan Citizenship Japanese
Post Office Address c/o SONY CORPORATION
7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan

Full name of second joint inventor, if any Tomoshi OHDE
Second Inventor's Signature Date
Residence, Japan Citizenship Japanese
Post Office Address c/o Sony Computer Entertainment Inc.
2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan

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ASSIGNEE is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument; and

ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed, and will not execute, any agreement in conflict herewith; and

ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

Full name of sole or first inventor Yuji NISHITANI

Inventor's Signature _____ Date _____

Residence _____, Japan _____ Citizenship Japanese

Post Office Address c/o SONY CORPORATION
7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan

Full name of second joint inventor, if any Tomoshi OHDE

Second Inventor's Signature Tomoshi Ohde Date Dec. 25 2006

Residence Tokyo, Japan _____ Citizenship Japanese

Post Office Address c/o Sony Computer Entertainment Inc.
2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan